

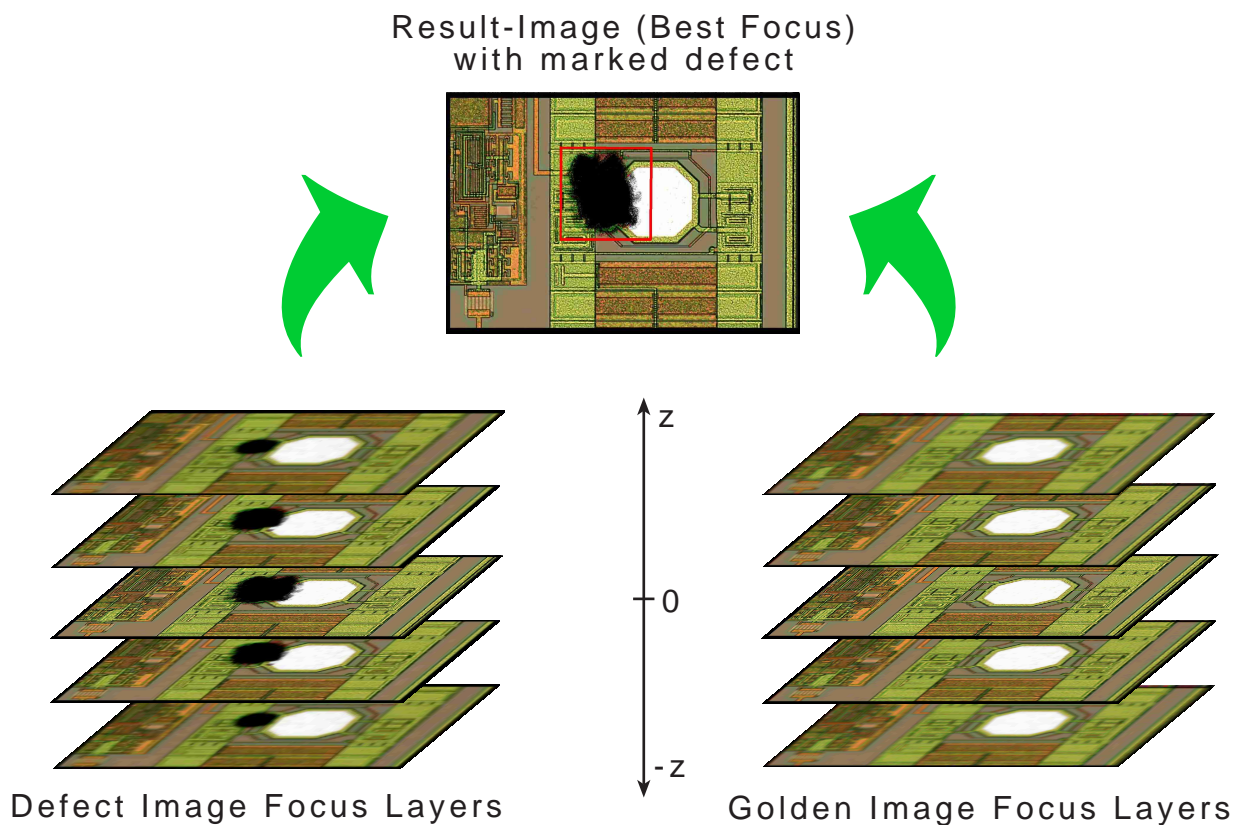
## TDA-Technology (example: Wafer Defect Recognition)

The TDA-Technology software is a solution for the detection of differences in image data. Comparing matching image data in small parts it may be used for defect- detection of microscopic wafer images in the semiconductor industry.

The main feature of the TDA-Technology is to compare 3-dimensional image data whereas the 3-D image data consists of multiple 2D image data. In the case of wafer images it is an image stack of multiple- focus layers. For defect detection a golden

(reference) image , generated from a non-defective area, is used to find differences. The result describes the location and the size of the defect in all three dimensions. Easy integration into any other software package is guaranteed by the TDA-Technology add-on library (DLL). It also provides functionality for reading and writing multiple-page TIFF files.

It may also be used for defect- detection in non-3D image data or spotting the best focus layer of a image stack.



### Features:

- Input : Multi-Layer-Image (defect stack and reference stack); 24Bit-RGB
- Output : Best-Focus layer; defect size and location
- Add-on library (DLL)
- Multi-page TIFF-Format support: Functions for reading and writing Multi-TIF images